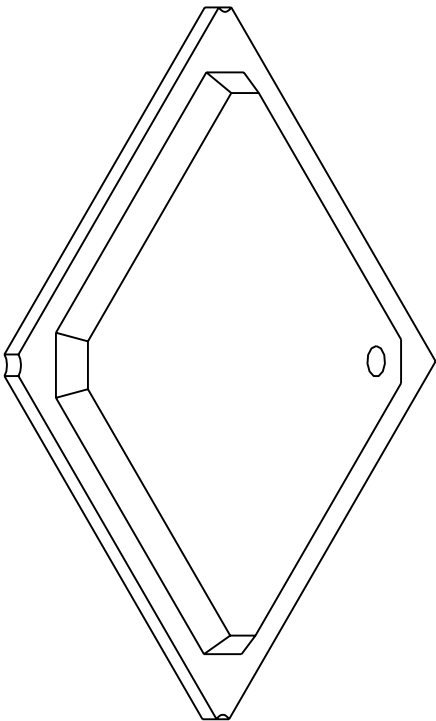


REVISIONS				
DCN	REV	DESCRIPTION	DATE	APPROVED
	01	ADD "GREEN" BBG NOMENCLATURE	10/20/04	TU VU



NOTES: UNLESS OTHERWISE SPECIFIED

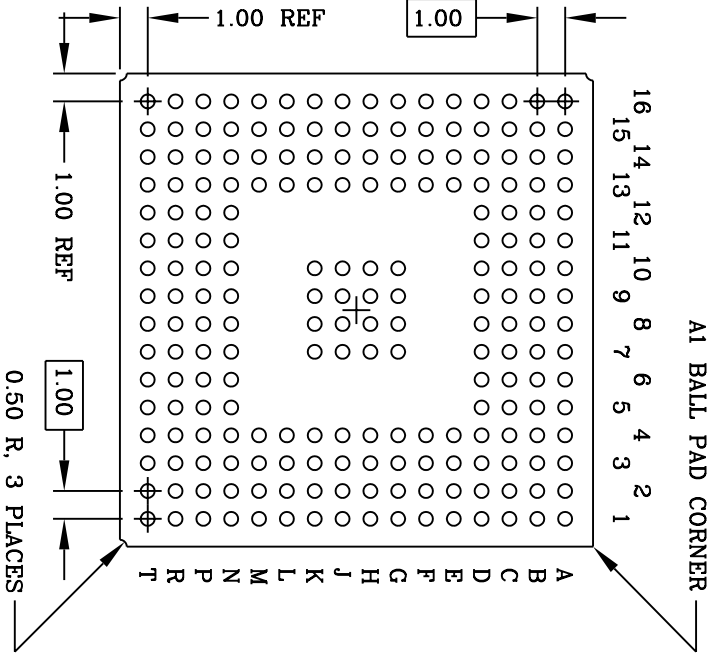
- ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.
- THE BASIC SOLDER BALL GRID PITCH IS 1.00mm.
- THE MAXIMUM SOLDER BALL MATRIX SIZE IS 16 X 16.
- REFERENCE SPECIFICATIONS:
A. AAWW SPEC #001-0531-2234: PACKING OPERATION PROCEDURE.
B. AAWW SPEC #001-0519-2062: MARKING.
C. THIS DRAWING CONFORMS TO THE JEDEC REGISTERED OUTLINE MO-151/C, VARIATION AAF-1 EXCEPT FOR aaa, b, AND A1 DIMENSIONS.
JEDEC(AMKOR) DIM MIN NOM MAX

aaa	0.20(0.15)	0.20(0.15)	0.60(0.50)
A1	0.40(0.30)	0.50(0.40)	0.60(0.50)
b	0.50(0.40)	0.60(0.50)	0.70(0.60)

DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM Z.

PRIMARY DATUM Z AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

A1 BALL PAD CORNER I.D. FOR PLATE MOLD: TO BE MARKED BY INK.
AUTO MOLD: DIMPLE TO BE FORMED BY MOLD CAP.

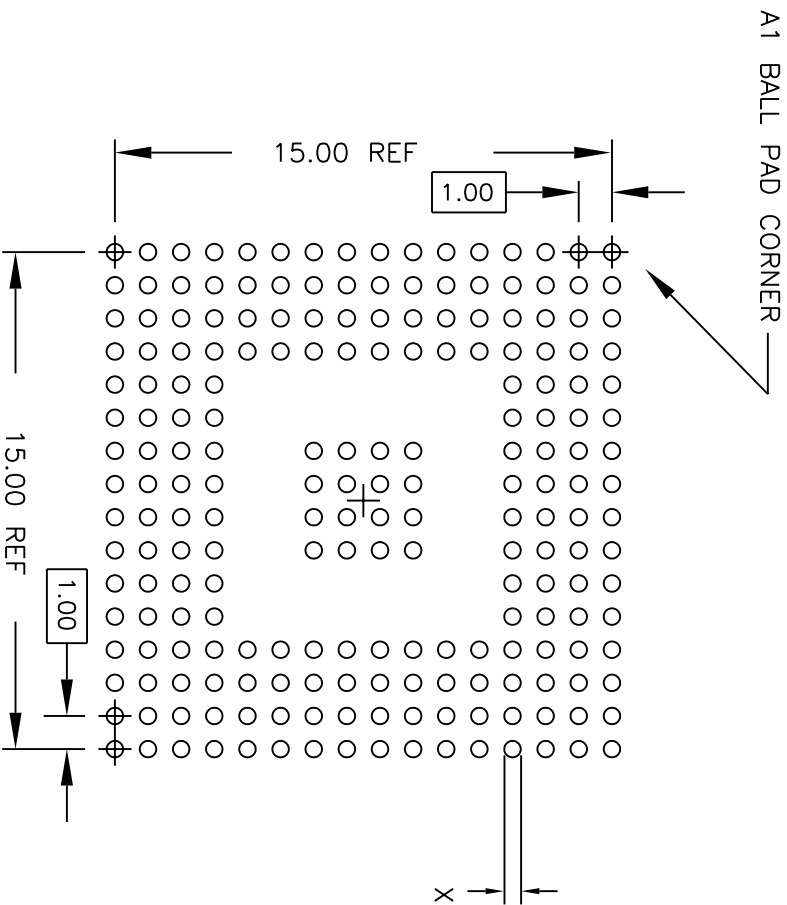


BOTTOM VIEW
(208 SOLDER BALLS)

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS X.XX ±0.06 X.XXX ±0.03				
APPROVALS	DATE	TITLE:		
DRAWN <i>p3/p</i>	10/23/00	BB/BBG 208 PACKAGE OUTLINE 17.0 X 17.0 mm BODY PBGA		
CHECKED		DRAWING No. PSC-4097		
		SIZE	SCALE	REV
		C	N/A	01
DO NOT SCALE DRAWING				
SHEET 2 OF 3				

REVISIONS				
DCN	REV	DESCRIPTION	DATE	APPROVED
	01	ADD "GREEN" BBG NOMENCLATURE	10/20/04	TU VU

RECOMMENDED LAND PATTERN DIMENSIONS



SYMBOL	MIN	NOM	MAX
X	.35	.40	.45

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS							
DECIMAL				INTEGRATED DEVICE TECHNOLOGY, INC.			
X.X ±0.10				2975 Slender Way, Santa Clara, CA 95050			
X.XX ±0.05				(408) 727-6116 FAX (408) 492-8074			
X.XXX ±0.03				WWW.IDT.COM			
APPROVALS		DATE		TITLE:			
DRAWN <i>DP/p</i>		10/23/00		BB/BBG 208 PACKAGE OUTLINE			
CHECKED				17.0 X 17.0 mm BODY PBGA			
DRAWING No.		PSC-4097		SIZE		C	
				SCALE		N/A	
				REV		01	
DO NOT SCALE DRAWING				SHEET 3 OF 3			